

Claims

1. A method for manufacturing a USB electronic key, whereby a microcircuit is cut out from a tape having a plurality of microcircuits, each microcircuit 5 defining USB-format contact pads and carrying an electronic component connected to the pads;

10 said method being characterized in that it further comprises the following step whereby, in a single operation, the thickness of the microcircuit is adjusted at least in the area of the contact pads, so as to have a thickness that conforms to the USB Standard.

15 2. A manufacturing method according to claim 1, characterized in that the adjustment is achieved by a casing (64, 66, 67, 68) comprising at least one bottom half-shell (66) disposed at least under the contact pads (57).

20 3. A manufacturing method according to claim 2, characterized in that the bottom half-shell is interfitted with a top half-shell (67) covering a zone of the microcircuit (62) that lies outside the contact pads.

25 4. A manufacturing method according to claim 1, characterized in that the adjustment is achieved by inserting the microcircuit into a shell (68) having an access (69) on a rear edge.

30 5. A manufacturing method according to claim 1, characterized in that the adjustment is achieved by forming an overmolded portion (64) over the microcircuit (100).

6. A manufacturing method according to claim 1, characterized in that the microcircuit is fastened to the bottom shell (66).

5 7. A manufacturing method according to claim 6, characterized in that the microcircuit is fastened by adhesive bonding or by tight-fitting cross-wise at least.

10 8. A manufacturing method according to any preceding claim, characterized in that the electronic component is disposed at a location offset from a 10 location (63) of the contact pads.

15 9. A manufacturing method according to any preceding claim, characterized in that the electronic component is disposed on the same top face of the microcircuit as the contact pads.

20 10. An electronic key including a microcircuit defining USB-format contact pads and carrying at least one electronic component (60, 61) connected to the pads, said electronic key being characterized in that the contact pads (57) are disposed on a dielectric having a thickness of less than 200  $\mu\text{m}$ ;

25 and in that it has its thickness adjusted by portion (66) of material overmolded over the microcircuit, at least in the area of and below a location of the contact pads, so that its microcircuit thickness conforms to the USB Standard.

11. An electronic key according to claim 10, characterized in that the overmolded portion is suitable for subsequently receiving a covering.

12. An electronic key comprising a microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, said electronic key being characterized in that the contact 5 pads (57) are disposed on a dielectric having a thickness of less than 200  $\mu\text{m}$ ;

and in that it has its microcircuit thickness adjusted by a bottom shell (66), at least in the area of a location (63) of the contact pads, so that its 10 microcircuit thickness conforms to the USB Standard.

13. An electronic key according to claim 11, characterized in that the bottom half-shell is interfitted with a top half-shell (67) which covers a zone (62) of the microcircuit that lies outside the 15 location (63) of the contact pads.

14. An electronic key according to claim 12 or claim 13, characterized in that it has an access (69) for inserting the microcircuit on a rear edge of its shell.